

L Number	Hits	Search Text	DB	Time stamp
1	5891	((257/656) or (257/657) or (257/458) or (257/619) or (257/620) or (257/621) or (257/622) or (257/623) or (438/59) or (438/167) or (438/622)).CCLS.	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/09/30 10:57
2	161	((257/656) or (257/657) or (257/458) or (257/619) or (257/620) or (257/621) or (257/622) or (257/623) or (438/59) or (438/167) or (438/622)).CCLS.) and (pin adj diode rectifier adj diode)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/30 10:58
-	0	("spitz.in.near2richard.in.").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/30 09:00
-	42	spitz.in. near2 richard.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/29 17:07
-	0	rectifier adj diode and clock adj (frequency frequencies) and switching adj (rate time) and thickness.ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/29 17:09
-	4	rectifier adj diode and clock adj (frequency frequencies) and switching adj (rate time) and thickness	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/29 17:10
-	433	257/101	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/29 17:12
-	354	257/104	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/29 17:19
-	3080	rectifier adj diode.ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/29 17:20
-	86	rectifier adj diode.ti,ab,clm. and thickness	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/29 17:40
-	2	914404.ap.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/29 18:26
-	2	de-4135258\$-\$\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/29 21:12
-	3	("4220963").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/29 18:30
-	0	("fr-2319972\$-\$\$.did.").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/29 18:30

-	0	("fr-2319972\$-\$\$.did. ").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/29 18:30
-	0	fr-02319972\$-\$\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/29 18:31
-	1	fr-2319972\$-\$\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/29 18:31
-	64	rectifier adj diode.ti,ab,clm. and 257/\$9.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/29 21:20
-	272	PIN adj diode.ti,ab,clm. and 257/\$9.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/29 21:28
-	510	((257/656) or (257/657)).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/29 21:28
-	95	((257/656) or (257/657)).CCLS.) and 438/\$9.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/29 21:29
-	0	metallisation near5 PIN adj diode near12 wafer near6 cutting	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/30 09:27
-	0	street near12 dicing and metallization near12 backside	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/30 09:28
-	7	street and (dice dicing) and metallization near12 backside	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/30 09:29
-	2	("5689091").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/30 09:30
-	20415	(cut cutting dice dicing) near6 wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/30 09:30
-	96	(cut cutting dice dicing) near6 wafer and (metallization metallisation metallize metallise) near6 (top upper front top-side front-side) and (metallization metallisation metallise metallize) near6 (bottom lower back backside back-side)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/30 09:32

-	50	(cut cutting dice dicing) near6 wafer and (metallization metallisation metallize metallise) near6 (top upper front top-side front-side) and (metallization metallisation metallise metallize) near6 (bottom lower back backside back-side) and method.clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/30 09:33
-	15	(cut cutting dice dicing) near6 wafer and (metallization metallisation metallize metallise) near6 (top upper front top-side front-side) and (metallization metallisation metallise metallize) near6 (bottom lower back backside back-side) and (method near6 (metal metallizing metallization)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/30 09:37
-	0	((method process) near12 (metallization metallizing metallising metallisation) near12 (cutting dicing cut dice)).ti,ab,clm. and street	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/30 09:38
-	36	((method process) near12 (metallization metallizing metallising metallisation) near12 (cutting dicing cut dice)).ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/30 09:38
-	14	((method process) near12 (metallization metallizing metallising metallisation) near12 (cutting dicing cut dice)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/30 09:43
-	0	street near12 dicing near12 metallization	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/30 09:43
-	84	dicing near12 metallization	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/30 09:43
-	7	dicing near12 metallization.clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/30 10:48